



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D  *: Required Field

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2016-03-23
<b>Contact Name *</b>	Refer to "Supplier Comment" section	<b>Contact Title</b>	Refer to "Supplier Comment" section
<b>Contact Phone *</b>	Refer to "Supplier Comment" section	<b>Contact Email *</b>	Refer to "Supplier Comment" section
<b>Authorized Representative *</b>	Floriana San Biagio	<b>Representative Title</b>	AMG Materials Declaration Champion
<b>Representative Phone *</b>	Refer to "Supplier Comment" section	<b>Representative Email *</b>	Refer to "Supplier Comment" section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/internet/com/support/online_tech_support.jsp">http://www.st.com/internet/com/support/online_tech_support.jsp</a>		

**Uncertainty Statement**

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**Legal Statement**

<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
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**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	E1B2*UF66JC2	A	ZY1A	2016-03-23
Amount	UoM	Unit type	ST ECOPACK Grade	
240	mg	Each	ECOPACK® 3	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used o	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	10.20x 5.30x 1.74	28	flat	
Comment	Package: B2 SSOP 28 10.2x5.3; MDF valid fro ST3237EBPR			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-17th December 2015				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	E1B2*UF66JC2					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	9.199	mg	supplier	die	Silicon (Si)	7440-21-3		8.874	mg	964670	36975
Die				supplier	metallization	Aluminium (Al)	7429-90-5		0.073	mg	7936	304
Die				supplier	metallization	Copper (Cu)	7440-50-8		0.001	mg	109	4
Die				supplier	Passivation	Silicon Nitride	12033-89-5		0.027	mg	2935	113
Die				supplier	Passivation	Silicon Oxide	7631-86-9		0.125	mg	13588	521
Die				supplier	polymer die coating	PIX1 Gamma-butyrolactone	96-48-0		0.099	mg	10762	413
leadframe	Copper & its alloys	69.339	mg	supplier	alloy	Copper (Cu)	7440-50-8		65.797	mg	956894	274154
leadframe				supplier	alloy	Iron (Fe)	7439-89-6		1.62	mg	23560	6750
leadframe				supplier	alloy	Zinc (Zn)	7440-66-6		0.081	mg	1178	338
leadframe				supplier	alloy	Phosphorus (P)	7723-14-0		0.02	mg	291	83
leadframe				supplier	coating	Silver (Ag)	7440-22-4		1.243	mg	18077	5179
die attach	Other Organic Materials	2.676	mg	supplier	glue	Resin	28064-14-4		0.557	mg	210030	2321
die attach				supplier	glue	Silver (Ag)	7440-22-4		1.855	mg	699472	7729
die attach				supplier	glue	Metal Oxide	1309-37-1		0.08	mg	30166	333
die attach				supplier	glue	Amine	Proprietary		0.08	mg	30166	333
die attach				supplier	glue	Gamma Butyrolactone	Proprietary		0.08	mg	30166	333
Bonding Wires	Precious metals	0.611	mg	supplier	wire	Gold (Au)	proprietary		0.606	mg	1000000	2525
encapsulation	Other Organic Materials	156.218	mg	supplier	molding compound	Multi-aromatic Resin	proprietary		11.618	mg	74995	48408
encapsulation				supplier	molding compound	SiO2 Filler	14808-60-7		133.228	mg	860002	555117
encapsulation	Other Organic Materials	156.218	mg	supplier	molding compound	Carbon Black	proprietary		0.775	mg	5003	3229
encapsulation				supplier	molding compound	Epoxy Cresol Novolac	proprietary		3.098	mg	19998	12908
encapsulation				supplier	molding compound	Phenol Resin	Proprietary		6.197	mg	40002	25821
finishing	Other inorganic materials	3.895	mg	supplier	connection coating	Tin (Sn)	proprietary		3.863	mg	1000000	16096